



3D University Research Summit

May 5th, 2011

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Summit Goals

- Identify the most critical industry challenges that 3D System Integration can address, and the new applications it can enable
- Help define the key role that academia can play in making it happen

Agenda

12:00 PM	Welcome, Summit Goals	Jon Candelaria, SRC
12:10 PM	State-of-the-3D Industry: Future Opportunities & Challenges	Francoise von Trapp, analyst
12:50 PM	3D Through Si Stacking – an IFM Perspective	Riko Radojcic, Qualcomm
1:30 PM	Future High-Performance Processing Systems Enabled by 3D Integration	Bob Conn, RTI
2:10 PM	3D Test & CAD Challenges/Opportunities	Bob Patti, Tezzaron
2:50 PM	Industry Speaker's Q&A	All
3:05 PM	SRC-FCRP 3D Portfolio Overview	Sung-Kyu Lim, GIT
3:45 PM	SRC-GRC 3D Portfolio Overview	Madhavan Swaminathan, (GIT) Paul Franzon (NCSU), Yuan Xie (PSU)
4:25 PM	Wrap-up	